



# Data Sheet

Customer:	
Part No:	CL-BIT1608DLG-02
Sample No:	

Description:

Item No:

1608 SMD Green Color

Customer				
Check Inspection		Approval	Date	





# CL-BIT1608DLG-02

#### Features

\_1.6mmX0.8mm SMT LED, 0.95mm THICKNESS. \_LOW POWER CONSUMPTION. \_WIDE VIEWING ANGLE. \_IDEAL FOR BACKLIGHT AND INDICATOR. \_VARIOUS COLORS AND LENS TYPES AVAILABLE. \_PACKAGE: 4000PCS / REEL. \_RoHS COMPLIANT.

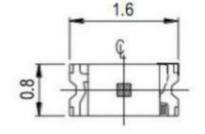
#### Description

The GREEN source color devices are made with GaN on Sapphire Light Emitting Diode. Static electricity and surge damage the LEDS. It is recommended to use a wrist band or

anti-electrostatic glove when handling the LEDs.

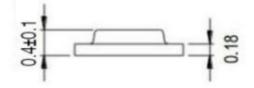
All devices, equipment and machinery must be electrically grounded.

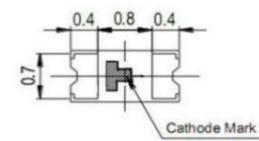
#### **Package Dimensions**



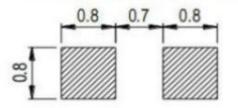


Polarity





Recommended Solder Pad



#### Notes:

1. All dimensions are in millimeters (inches).

2. Tolerance is  $\pm 0.1 (0.004")$  unless otherwise noted.

3. Specifications are subject to change without notice.





**Selection Guide** 

Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle	
			Min.	Тур.	<b>2</b> θ <b>1/2</b>	
CL-BIT1608DLG-02	GREEN (GaN)	WATER CLEAR	400	700	120	

Note:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λD	Dominant Wavelength	GREEN	517.5	527.5	nm	IF=20mA
Δλ1/2	Spectral Line Half-width	GREEN	25		nm	IF=20mA
С	Capacitance	GREEN	105		pF	VF=0V;f=1MHz
VF	Forward Voltage	GREEN	2.6	3.3	v	IF=20mA
IR	Reverse Curren	GREEN		2	uA	VR = 7V

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical

accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous Intensity: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters

#### Absolute Maximum Ratings at TA=25°C

Parameter	GREEN	Units
Power dissipation	135	mW
DC Forward Current	30	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	I

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.





Luminous Intensity Bin Limits

BIN Code	Test Condition @20mA		
DLG	Vfmin(v)	Vfmax (v)	
1	2.6	2.7	
2	2.7	2.8	
3	2.8	2.9	
4	2.9	3.0	
5	3.0	3.1	
6	3.1	3.2	
7	3.2	3.3	

#### Forward Voltage Bin Limits

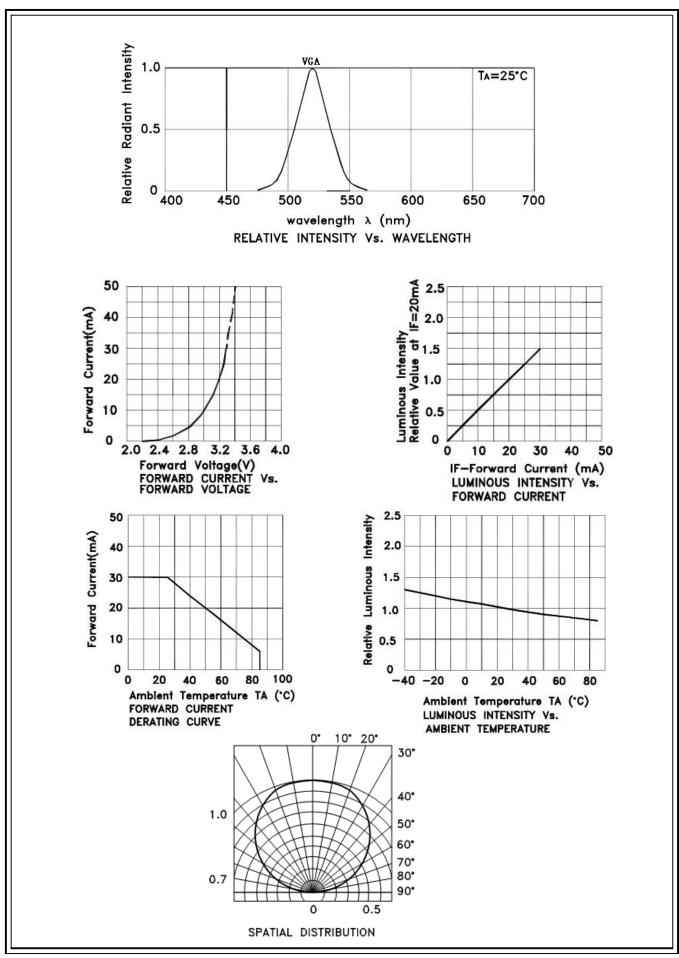
BIN Code	Test condition: @20mA		
DLG	IVmin(mcd)	IVmax (mcd)	
1	400	500	
2	500	600	
3	600	700	

### Dominant Wavelength BIN Limits

BIN Code	Test condition: @20mA		
DLG	$\lambda_{dmin}(nm)$ $\lambda_{dmax}(nm)$		
1	517.5	519.5	
2	519.5	521.5	
3	521.5	523.5	
4	523.5	525.5	
5	525.5	527.5	











#### RELIABILITY (1) TestItemsandResults Number of (Hours/ Reference NO. Test Item Test Conditions Sample Damaged Cycles) Standard -40 °C - 25 °C - 100 °C - 25 °C 100 Temperature 1 JEITA ED-4701 20 0/20 Cycles Ċycl e 30min 5min 30min 5min -40°C~100°C 500 Thermal 2 MIL-STD-202G 20 0/20 Cycles shock 15min 15min Hi gh JEITA ED-4701 1000 Ta=100°C 20 0/20 3 Temperature Hours 200 201 Storage Low JEITA ED-4701 1000 Temperature Ta=−40°C 20 0/20 4 Hours 200 201 Storage $Ta=25\pm5^{\circ}C$ Room 1000 Temperature 20 0/20 5 Hours IF=20mA Life Test Ta=60°C RH=85% Hi gh 1000 Temperature 6 20 0/20 Hours High Humidity IF=20mA Life Test JEITA ED-4701 Tso1= $235^{\circ}$ C $\pm 5^{\circ}$ C, 5 sec Solderability 1 time, (Reflow Soldering) 7 10 0/105sec 300 303 (Using Flux, Lead Solder) **Resistance** Tso1=250℃, 10 sec JEITA ED-4701 to Soldering 2 time. 8 Pre Treatment: 35 °C 10 0/10Heat 10sec 300 301 (Reflow 95% RH96 Hrs Soldering)

The above test items such as differences or special customer specific requirements according to the actual situation in accordance with the requirements of customers to try the requirements with the customer, the customer is not required by our test standard test. Different products using different current test





# CL-BIT1608DLG-02

# 5. Cautions

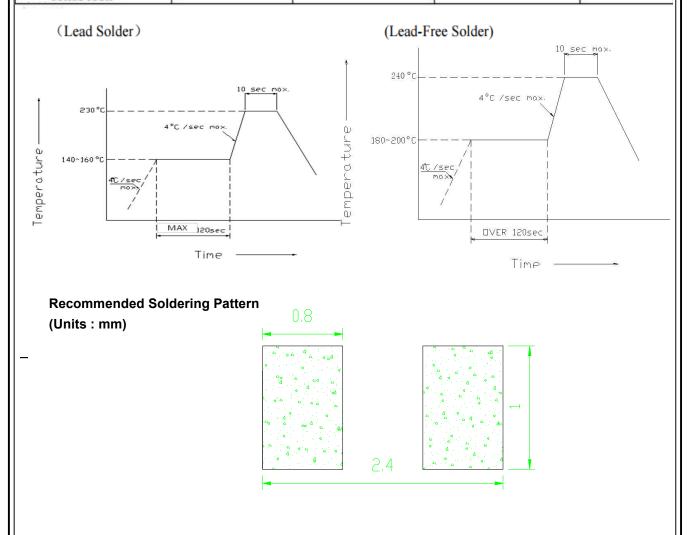
#### (1) Soldering Conditions

Number of reflow process shall be less than 2 times and cooling process to normal temperature

is required between first and Second soldering process.

(Recommended soldering conditions)

	Reflow Solde	ering	Manual Sold	lering
Pre-heat	Lead Solder	Lead-free Solder	Temperature Soldering	350° C Max. 3 sec. Max.
Pre-heat time Peak temperature Soldering time Condition	140 ~ 160° C 120 sec. Max. 230° C Max. 10 sec. Max.	180 ~ 200° C 120 sec. Max. 240° C Max. 10 sec. Max.	time	(one time only)







# CL-BIT1608DLG-02

- (2) Static Electricity
  - It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.
  - All devices, equipment and machinery must be properly grounded.

Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the

- LEDs do not light at the low current. Criteria : (VF > 2.0V at IF=0.5mA)
- (3) Moisture Proof Package
- It is recommended that moisture proof package be used .

#### (4)Cautions:

- 4.1.Please check if there is air leak before opening the package, if so, please return the goods back to take drying process for later using.
- 4.2 Products can be used within 15days after packaging, after that, they must be:
  - 4.2.1 Soldered within 24 hrs
  - 4.2.2 Used in the condition:  $30^{\circ}$ C within and  $60^{\circ}$ RH below
  - 4.2.3 Stored in 30%RH for moisture below.
- 4.3.Products cannot be used for and over 15days after being packaged unless opening the package and take drying our process in 85°C/6H.
- 4.4.Products not be used for or over 60days after being packaged please return back to take drying out and packaging process for forward using.
- 4.5.Products not be used after opening the package need to be dried out for  $85^\circ \text{C}/6\text{H}$





## PACKAGING

The LEDs are packed in cardboard boxes after taping.

